

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Heisley	Docket No.: TI-33886.1
Serial No.: TBD	Examiner: TBD
Filed: 3/2/2004	Art Unit: TBD
For: WAFER ALIGNMENT DEVICE AND METHOD	

PRELIMINARY AMENDMENT

Honorable Assistant Commissioner
of Patents
Washington, D.C. 20231

"EXPRESS MAILING" Mailing Label No. EL547742786US

Date of Deposit: 3-2-04

Prior to the examination of the above identified application, please amend the above referenced Application as follows: